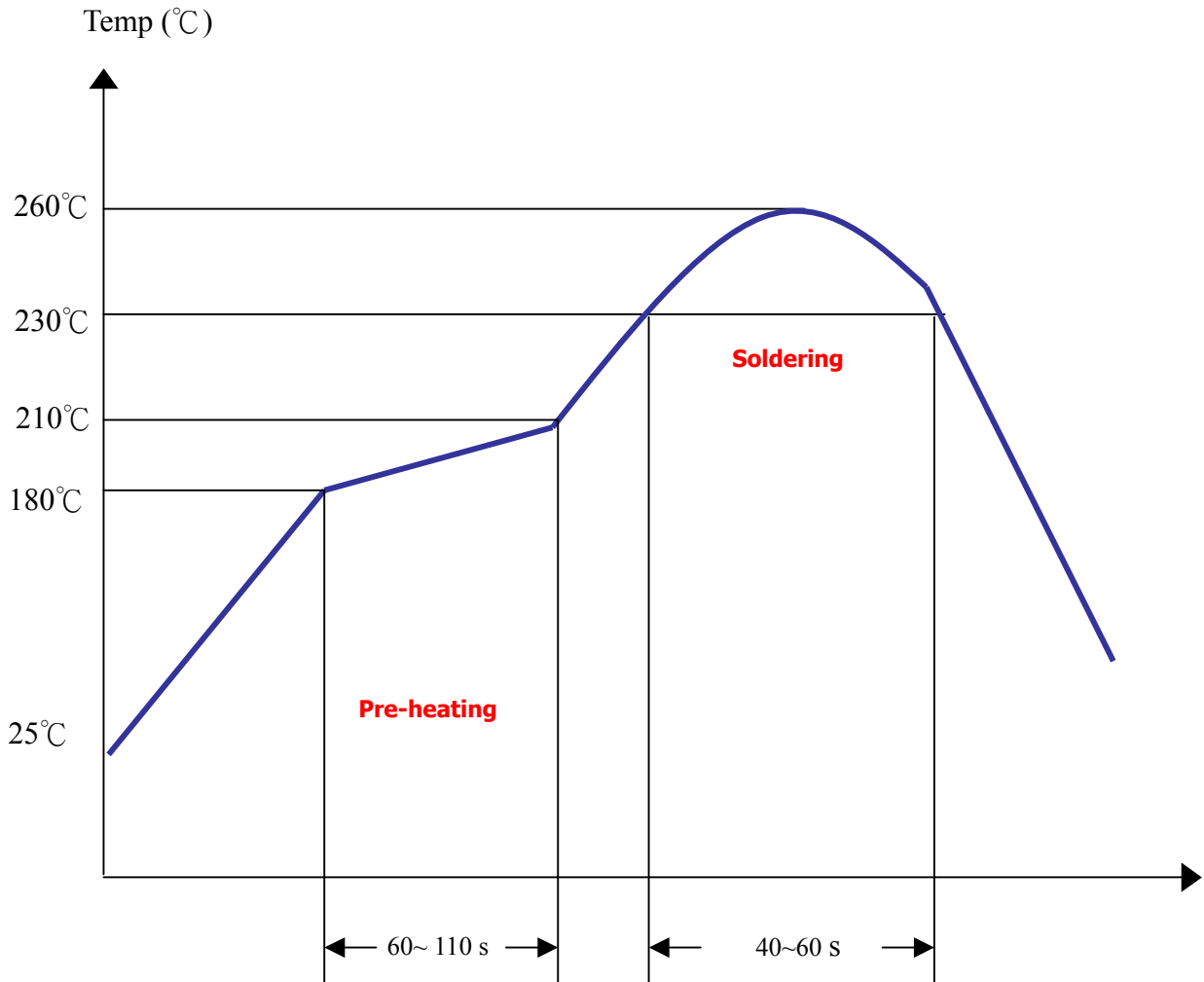




SMT Reflow Profiles for ICs with Pb-Free assembly



Testing Contents:

<u>Stage</u>	<u>Condition</u>	-
<u>Duration</u>		
1'st Ram Up	3.0+/-2°C/sec	
Preheat	180°C~210°C	60~110 secs
2'nd Ram Up	2.0+/-1°C/sec	
Solder Joint	230°C above	40~60 secs
Peak Temp	260+5/-0°C	5 secs
Rpmp Down rate	-6°C/sec max	